ABSTRACT

CHUCK TABLE

A chuck table holds under suction a front side of a wafer which includes a device region including a plurality of devices, each having a plurality of electrode bumps, formed in a plurality of areas demarcated in a grid pattern, and an outer peripheral extra region surrounding the device region. The chuck table includes a holding surface for facing the electrode bumps and holding under suction the device region of the wafer, and an outer peripheral extra region support surrounding the holding surface and including an elastic member projecting beyond the holding surface for supporting the outer peripheral extra region of the wafer. The outer peripheral extra region support projects from the holding surface by a distance corresponding to the height of the electrode bumps.

(Figure 5)